

APPROVAL SHEET

AOT MODEL NAME	4014PCT
AOT PART NUMBER	4014C-W334
CUSTOMER NAME	General
DATE	2021/Sep
VERSION	01

MAKER			CUSTOMER			
Prepared	pared Checked Approved					
Yo.Chen						

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Revision Note

Date	Revision	Page	Version
2021-09-14	Initiate Document	17	1



Package Outline

Type Number: 4014C-W334 Unit: mm, Tolerance: ± 0.2 mm

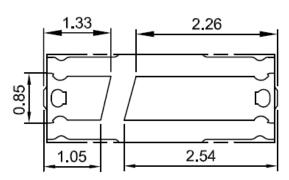
70p View

4.0

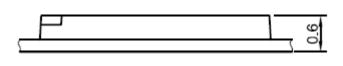
3.8

3.47

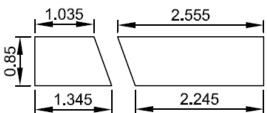
Bottom View

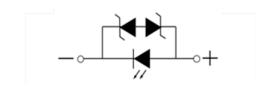


Front View



Recommended soldering pad design





Item	Materials
Package	Heat-Resistant Polymer
Encapsulating Material	Silicone Resin(with phosphor)
Electrode	Ag Plating Copper Alloy

- Single blue chip.
- High brightness SMD.
- Compact package outline (LxWxH) of 4.0 mm x 1.4 mm x 0.6 mm.
- Compatible with reflow soldering.
- Complies with RoHS Directive.



Optical/Electronic Characteristics (Ts=25°C)

AOT Reading Standards								
Item Symbol Condition Min Typ Max Unit								
Forward Voltage	V _F	I _F = 60mA	2.7	-	2.9	V		
Luminous Flux	φν	I _F = 60mA	23	-	27	lm		
Thermal Resistance	R _{thj-s}	I _F = 60mA	18 (T _S =25°C)	24 (T _S =25°C)	-	°C/W		

^{*} Tolerance of measurements of the Forward Voltage is ± 0.05 V.

Absolute Maximum Ratings (Ts=25°C)

Item	Symbol	Maximum Value	Unit
Forward Current	I _F	240	mA
Peak Pulse Forward Current	I _{FP}	470	mA
LED Junction Temperature.	T _j	125	°C
Operating Temperature.	T _{opr}	-35 ~ +85	°C
Storage Temperature.	T _{stg}	-40 ~ +100	°C
Power Dissipation	P _D	696	mW
Soldering Temperature	T _{sld}	Reflow Soldering 260°C,10sec	
Forward Voltage at Low Current	V _{F2}	>1.9 (@1uA)	

^{*} I_{FP} Conditions : Pulse Width ≤10msec, and duty ≤1/10

^{*} Tolerance of measurements of the Luminous Flux is \pm 7%.

^{*} Max condition is not guarantee for life time



Solid-State Light. Done Right.

Group Definition of Forward Voltage

Rank	Condition	V _F (V)
S2	T _A =25°C	2.7 ~ 2.8
S3	I _F =60mA	2.8 ~ 2.9

Group Definition of of Wavelength

Rank	Condition	W _D (nm)
W458	T _A =25°C	458 ~ 460
W460	I⊧=60mA	460 ~ 462

Group Definition of Brightness

Rank	Condition	Luminous Flux(Im)
H18		18 ~ 19
H19		19 ~ 20
H20	T _A =25°C	20 ~ 21
H21		21 ~ 22
H22	I₅=60mA	22 ~ 23
H23		23 ~ 24
H24		24 ~ 25
H25		25 ~ 26

^{*}A shipment shall consist of LEDs in a combination of above ranks.

^{*}The percentage of each rank in the shipment shall be determined by AOT.

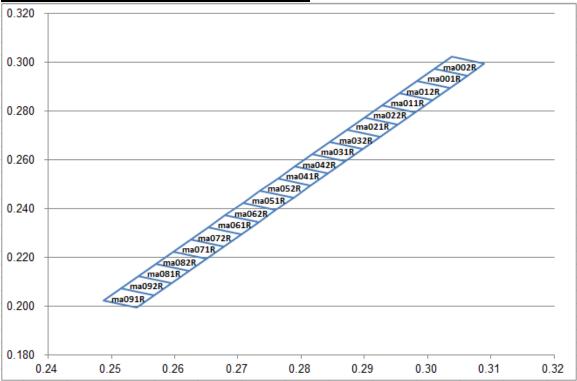
^{*}The ranking information of LEDs can be found on the reel label.

^{*}The tolerance limit Wp: ±1 nm



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Group Definition of Chromaticity Coordinate



Rank	х	у	Rank	х	у	Rank	х	у
	0.3011	0.2973		0.2983	0.2923		0.2955	0.2873
ma002R -	0.3039	0.3023	ma001D	0.3011	0.2973	ma012R	0.2983	0.2923
	0.3090	0.2995	ma001R	0.3063	0.2945	IIIau IZR	0.3035	0.2895
	0.3063	0.2945		0.3035	0.2895		0.3008	0.2845
	0.2928	0.2823		0.2900	0.2773		0.2873	0.2723
ma011R	0.2955	0.2873	ma022R	0.2928	0.2823	ma021R	0.2900	0.2773
IIIauTTK	0.3008	0.2845		0.2980	0.2795	IIIauz IIX	0.2953	0.2745
	0.2980	0.2795		0.2953	0.2745		0.2925	0.2695
	0.2845	0.2673	ma031R	0.2818	0.2623		0.2790	0.2573
ma032R	0.2873	0.2723		0.2845	0.2673	ma042R	0.2818	0.2623
maoszix	0.2925	0.2695	maosiix	0.2898	0.2645	mao4zix	0.2870	0.2595
	0.2898	0.2645		0.2870	0.2595		0.2843	0.2545
	0.2763	0.2523		0.2735	0.2473		0.2708	0.2423
ma041R	0.2790	0.2573	ma052R	0.2763	0.2523	OE4D	0.2735	0.2473
mao4 m	0.2843	0.2545	maoszit	0.2815	0.2495	ma051R	0.2788	0.2445
	0.2815	0.2495		0.2788	0.2445		0.2760	0.2395
	0.2680	0.2373		0.2653	0.2323		0.2625	0.2273
ma062R	0.2708	0.2423	ma061R	0.2680	0.2373	ma072R	0.2653	0.2323
mauuzn	0.2760	0.2395	IIIauu IIX	0.2733	0.2345	maurzix	0.2705	0.2295
	0.2733	0.2345		0.2705	0.2295		0.2678	0.2245



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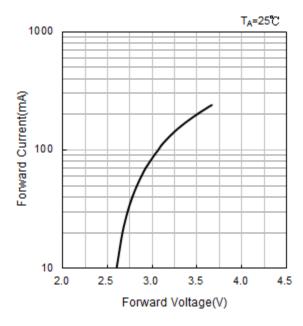
Solia State El	3							
ma071R	0.2598	0.2223		0.2570	0.2173		0.2543	0.2123
	0.2625	0.2273	ma082R	0.2598	0.2223	ma081R	0.2570	0.2173
IIIau IIX	0.2678	0.2245	madozix	0.2650	0.2195	IIIauu IIX	0.2623	0.2145
	0.2650	0.2195		0.2623	0.2145		0.2595	0.2095
	0.2515	0.2073		0.2488	0.2023			
ma092R	0.2543	0.2123	ma001D	0.2515	0.2073			
mauszk	0.2595	0.2095	ma091R	0.2568	0.2045			
	0.2568	0.2045		0.2540	0.1995			

Note: Chromaticity coordinate groups are measured with an accuracy of ±0.005.

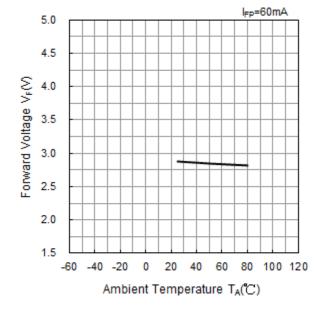


Optical and electrical characteristics

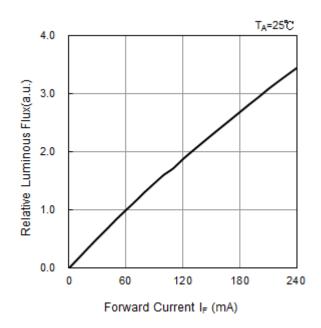
Forward Voltage vs. Forward Current



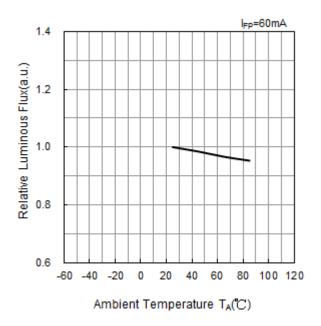
Ambient Temperature vs. Forward Voltage



Forward Current vs. Relative Luminous Flux

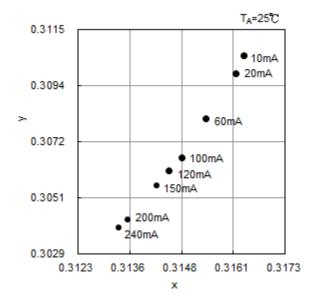


Ambient Temperature vs. Relative Luminous

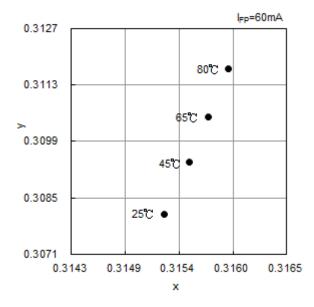




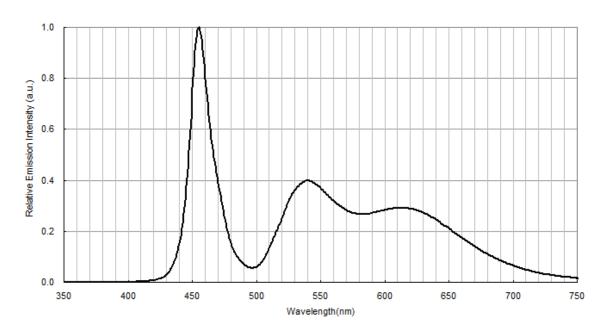
Forward Current vs.Chromaticity Coordinate



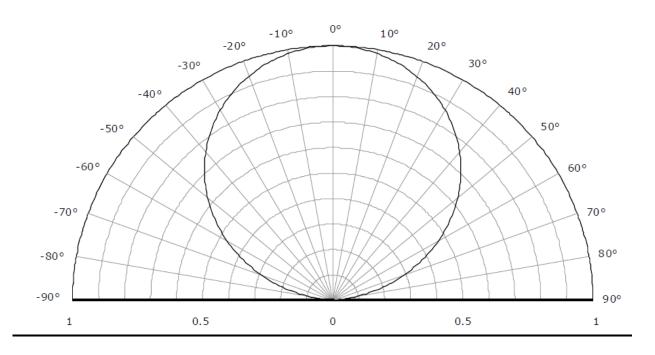
Ambient Temperature vs. Chromaticity Coordinate







Radiation Pattern(T_A=25°C,I_{FP}=60mA)





Recommended Reflow Soldering Conditions

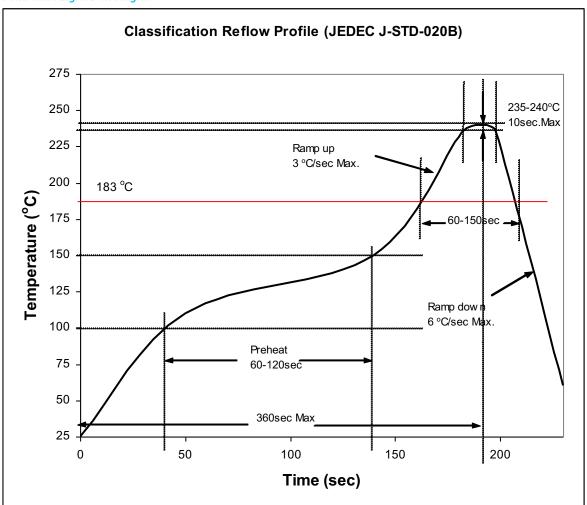
Surface Mounting Condition

In automatic mounting of the SMD LEDs on printed circuit boards, any bending, expanding and pulling forces or shock against the SMD LEDs should be kept min. to prevent them from electrical failures and mechanical damages of the devices.

Soldering Reflow

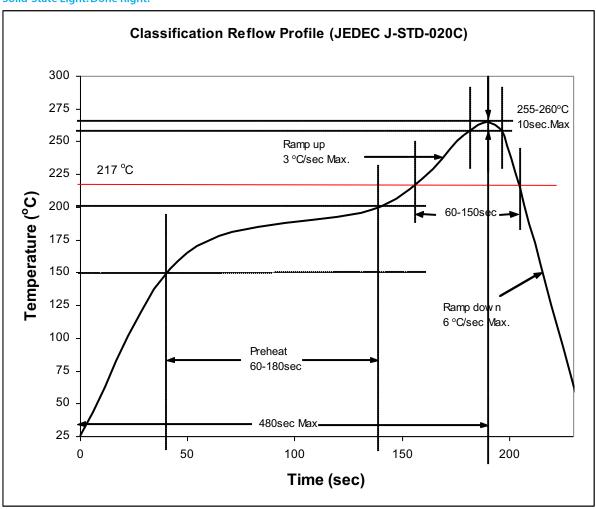
- -Soldering of the SMD LEDs should conform to the soldering condition in the individual specifications.
- -SMD LEDs are designed for Reflow Soldering.
- -In the reflow soldering, too high temperature and too large temperature gradient such as rapid heating/cooling may cause electrical & optical failures and damages of the devices.
- -AOT cannot guarantee the LEDs after they have been assembled using the solder dipping method.
- 1) Lead Solder





2) Lead-free Solder

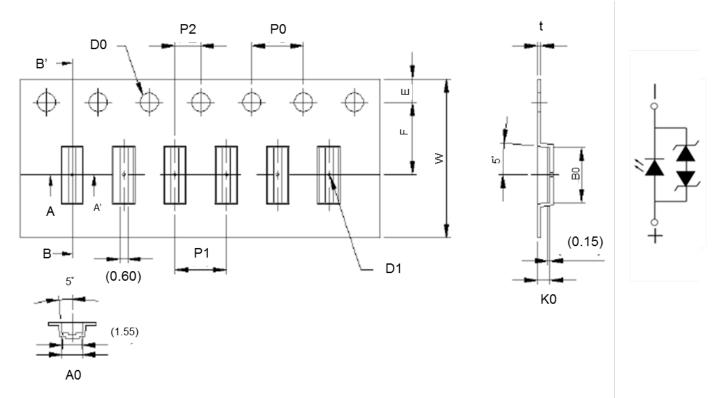




3) Manual Soldering Conditions

- Lead Solder
 - Max. 300 °C for Max. 3sec, and only one time.
- Lead-free Solder
 - Max. 350 °C for Max. 3sec, and only one time.
- There is possibility that the brightness of LEDs is decreased, which is influenced by heat or ambient atmosphere during reflow. It is recommended to use the nitrogen reflow method.
- After LEDs have been soldered, repair should not be done. As repair is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will be damaged by repairing or not.
- Reflow soldering should not be done more than two times.

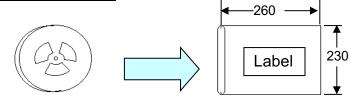




Item	Spec.	Tolerance(mm)	Item	Spec.	Tolerance(mm)
W	12.00	±0.20	P2	2.00	±0.05
E	1.75	±0.10	t	0.23	±0.05
F	5.50	±0.10	A0	1.55	±0.05
D0	1.50	±0.10,-0	В0	4.20	±0.05
D1	1.00	±0.10	K0	0.95	±0.05
P0	4.00	±0.10	α	Max 5°	
P1	4.00	±0.10			

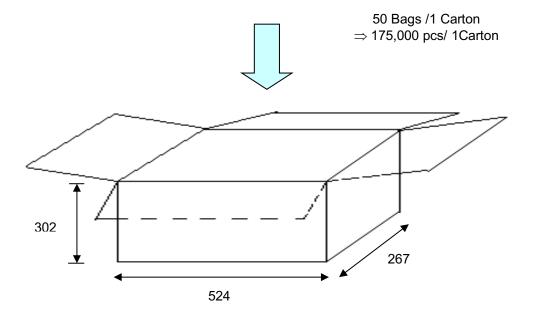


Solid-State Light. Done Right. Packing Formation

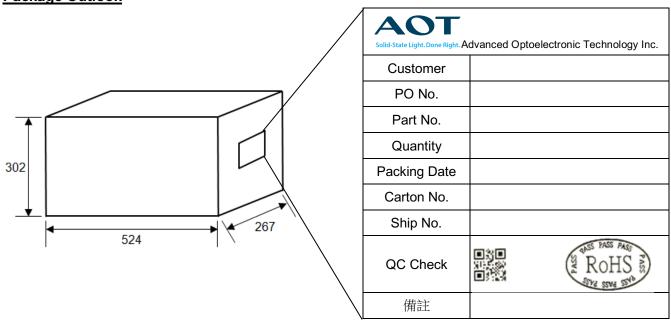


Diameter: 178 mm Width: 8 mm 3,500 pcs/Reel Antistatic Reel

MBB Bag +5g drying agent +Humidity card 1 Reel / Bag



Package Outlook





SAP. No.

SMD LED

Part Number: XXXXX-XXXX

Brightness : A
CIE : B
VF : C
Quantity : nn ea

Serial No : SM0yymmddxxxx

Cust. PN. : XXXXX-XXXX



A : Iv value.

B : CIE value noted

C: Vf value.

nn: Quantity of LED

SM0yymmddxxx: yy: year, mm: month, dd: day, xxxx: reel no.

*Reel Label to fill in practice data of all LED characteristic



Reliability Test

No.	Test Item	Standard Test	Test	Note	Number of
		Method	Conditions		Damaged
1	Room Temp. Life Test	Internal Ref.	T _A =25 °C,I _F =60mA	1000 hr	0/20
2	High Temp. Operation	JESD22-A108	T _A =65°C,I _F =60mA	1000 hr	0/20
3	High Temp. Operation	JESD22-A108	T _A =85°C,I _F =60mA	1000 hr	0/20
4	High Temp. Storage	JESD22-A103	T _A =100°C	1000 hr	0/20
5	Low Temp. Operation	JESD22-A108	T _A =-40°C,I _F =60mA	1000 hr	0/20
6	High Temp. and High Humidity Operation	JESD22-A119	60°C 90%RH,I⊧=60mA	1000 hr	0/20
7	Temperature and humidity cycle test	IEC68-2-38	25°C ~65°C ~-10°C,90% RH 24hr per cycle	10 cycle	0/20
8	Thermal Cycling Test	JESD22-A106	-40°C ~ 100°C ,30min Transform time 5min	300 cycles	0/50

Criteria for Judging Damage

Item	Symbol	Toot Conditions	Criteria for Judgement		
item		Test Conditions	Min.	Max.	
Forward Voltage	VF	I _F =60mA	-	*U.S.L×1.1	
Luminous Flux	φν	I==60mA	*L.S.L×0.7	-	

* U.S.L: Upper Standard Level * L.S.L: Lower Standard Level



Cautions

(1) Moisture Proof Package

The moisture proof package should be used to prevent moisture in the package as the moisture may Cause damage to optical characteristics of the LEDs.

The aluminum bag with zipper is used for moisture proof package. And, the moisture absorbent Material, Silica gel, is inserted into aluminum bag.

(2) Storage:

Storage Conditions

Before opening the package:

The LEDs should be kept at 30°C or less than 90%RH or less. The LEDs should be used within a year. When storing the LEDs, moisture proof packaging with absorbent material is recommended. After opening the package:

After open the package, the LED should be kept at 30°C, 60%RH or less. The LED should be soldered within 168 hours (7 days) after opening the package. If unused LEDs remain, it should be stored in moisture proof condition.

(3) Heat Generation

Thermal design of the end products is of paramount importance. The heat generation must be taken into design consideration when using the LED. The coefficient of the temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board, as well as other components.

(4) Static Electricity

Static electricity or surge voltage damages the LEDs. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LEDs. When inspecting the final products in which LEDs were assembled, it is recommended to check whether the assembled LEDs are damaged by static electricity or not. It is easy to find static-damaged LEDs by a light-on test or a Vf test at a lower current. (Below 1mA is recommended). Criteria: Vf >1.9V at Ir=1uA

(5) Cleaning

Use isopropyl alcohol as a solvent for cleaning the LEDs. The other solvent may dissolve the LEDs package and the epoxy.

Ultrasonic cleaning should not be done.

(6) Electrostatic Discharge (ESD)

The products are sensitive to static electricity or surge voltage, An ESD event may damage its die or reduce its reliability performance. When handling the products, measures against electro static discharge, including the followings, are strongly recommended.

Eliminating the charge;

Wrist strap, ESD footwear and garments, ESD floors

Grounding the equipment and tools at workstation



ESD table / shelf mat (conductive materials)

Proper grounding techniques are required for all devices, equipment and machinery used in the assembly of the products, Also note that surge protection should be considered in the design of customer products.

If tools or equipment contain insulating materials, such as glass or plastic, proper measures against electro static discharge, including the followings are strongly recommended.

Dissipating the charge with conductive materials

Preventing the charge generation with moisture

Neutralizing the charge with ionizer

(7) Others

When using the LEDs, it must care that the reverse voltage will not exceed the absolute maximum rating. The LED light is enough to injure human eyes, so it should avoid looking at LED light directly.

NOTE.

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